Docket No.:   005916 USA/FPS/MMCS/MC   PATENT/**OFFICIAL**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of   :
                                                :
Young Joseph PAIK   :
                                                :
Serial No. 09/998,384   : Group Art Unit: 2812
                                                :
Filed: November 30, 2001   : Examiner:

For: FEEDFORWARD AND FEEDBACK CONTROL FOR CONDITIONING OF
        CHEMICAL MECHANICAL POLISHING PAD

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the

Patent and Trademark Office is hereby directed to the documents listed on the attached form

PTO-1449. It is respectfully requested that the documents be expressly considered during the

prosecution of this application, and that the documents be made of record therein and appear

among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S.

filing date OR before the mailing date of a first Office Action on the merits. No certification or

fee is required.

This submission does not constitute a representation that a search has been made or that

no better art exists and does not constitute an admission or representation that any of the listed

documents is material or constitutes prior art. If it should be determined that any of the listed

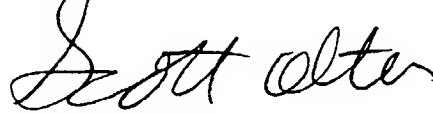documents does not constitute prior art under the United States law, Applicants reserve the right

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to present to the Office the relevant facts and law regarding the appropriate status of such document.

No certification or fee is believed to be required. However, the Commissioner is hereby authorized to charge any additional fees should any be required for this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

HALE AND DORR LLP

Scott M. Alter
Registration No. 32,879
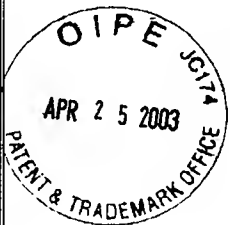
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	ATTY. DOCKET NO. 005916 USA/FPS/MMCS/MC	SERIAL NO. 09/998,384
INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)		
	APPLICANT Young Joseph PAIK	
	FILING DATE November 30, 2001	GROUP 2812

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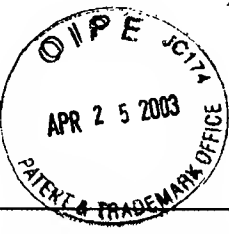| EXAMINER	DATE CONSIDERED

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APPLICANT Young Joseph PAIK		

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	0 869 652	10/07/98	Europe			X	
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	0 910 123	04/21/99	Europe			X	
	0 932 194	07/28/99	Europe			X	
	WO 00/00874	01/06/00	WIPO			X	
	2000-183001	06/30/00	Japan			X	

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation Yes	No
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	436383	05/28/01	Taiwan			X	
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